

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	12	((("6413850") or ("6402014") or ("6471115") or ("6213386") or ("6146920") or ("6460755")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 14:45
S2	1201	contact adj print\$3 and (solder or bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 14:13
S3	1026	contact adj print\$2 and (solder or bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 14:13
S4	331	contact adj print\$3 and (solder or bump) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 14:24
S5	35	((contact adj print\$3) same mask) and (solder or bump) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 14:42
S6	3	((contact adj print\$3) same mask) and bump and thermosetting adj resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 14:44
S7	75	((contact adj print\$3) same mask) and ("257"/\$ or "438"/\$).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 15:09
S8	83	((print\$3) same mask same squeegee) and ("257"/\$ or "438"/\$).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 15:44
S9	1227	438/107-108.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 15:26

S10	197	438/110.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 16:41
S11	531	438/113.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 16:42
S12	823	("438"/\$ or "257"/\$).ccls. and contact adj3 print\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/12/01 17:38
S13	34	("438"/\$ or "257"/\$).ccls. and contact adj3 print\$3 and @pd<"19800101"	USPAT	OR	OFF	2002/12/01 17:42
S14	249	semiconductor and contact adj3 print\$3 and @pd<"19800101"	USPAT	OR	OFF	2005/11/07 15:39
S15	0	semiconductor and (contact adj3 print\$3) and squeegee and @pd<"19800101"	USPAT	OR	OFF	2002/12/01 17:43
S16	70	semiconductor and (contact adj3 print\$3 same mask) and @pd<"19800101"	USPAT	OR	OFF	2002/12/01 17:44
S17	46	semiconductor and (contact adj3 print\$3 with mask) and @pd<"19800101"	USPAT	OR	OFF	2002/12/01 17:44
S18	1832	circuit and (print\$3 same squeegee)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/10 12:19
S19	459	(solder terminal) same ((insulat\$4 or polyimide) with (micrometer\$1 or micron\$1 or (micro adj meter\$1) or micro-meter\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 09:11
S20	464	memory and (polyimide with (micrometer\$1 or micron\$1 or (micro adj meter\$1) or micro-meter\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 09:12
S21	751	(memory or transistor) and (polyimide with (micrometer\$1 or micron\$1 or (micro adj meter\$1) or micro-meter\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 09:58

S22	4333	257/690,737,738,772.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:02
S23	1813	257/738,772.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:02
S24	2885	257/737,738,772.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:02
S25	1813	257/738,772.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:26
S26	190	257/738,772.ccls. and (micrometer\$1 micro-meter\$1 micron\$1 (micro adj meter\$1)) and polyimide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:27
S27	347	257/690,737,738,772.ccls. and (micrometer\$1 micro-meter\$1 micron\$1 (micro adj meter\$1)) and polyimide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 10:27
S28	12	((("5442482") or ("5887520") or ("6287893") or ("6313532") or ("6472249") or ("6472724"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 13:22
S29	1897	polyimide with (elasticity or elastic or "young's")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 14:00
S30	1889	polyimide with (elasticity or modulus or "young's")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 14:00
S31	981	DRAM and package and (resin polyimide) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 12:11

S32	340	DRAM and package and (resin polyimide) and solder adj bump\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 12:35
S33	0	"09486779"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 12:35
S34	3	'09/486779'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 12:37
S35	468	transistor same circumferential	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 12:43
S36	36	package and (transistor same circumferential)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 12:43
S37	0	package and (peripheral with transistor) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 13:02
S38	0	package and (peripheral with transistor\$1) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 13:03
S39	112	package and (peripheral with transistor\$1) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 15:43
S40	672	257/772,737,738,690.ccls. and @pd>"20041117"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 14:46
S41	443	438/107-108.ccls. and @pd>"20041117"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 15:27
S42	266	semiconductor and contact adj3 print\$3 and @pd>"20041117"	USPAT	OR	OFF	2005/11/07 15:40

S43	9	package and (peripheral with transistor\$1) and solder and @pd>"20041117"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 16:06
S45	854	((wafer substrate) and terminal and transistor and insulat\$3).clm.	US-PGPUB	OR	ON	2005/11/07 16:07